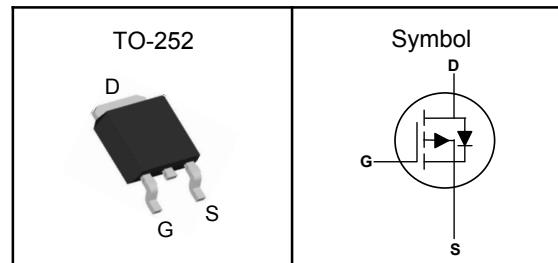


P-Channel Enhancement Mode MOSFET

Features

- Low R_{dson} for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

V_{DSS}	-100	V
$R_{DS(ON)-Typ}$	50	$\text{m}\Omega$
I_D	-30	A

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
V_{DSS}	Drain-Source Voltage	-100	V
V_{GSS}	Gate-Source Voltage	± 20	V
T_J	Maximum Junction Temperature	-55 to 175	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	-90	A
I_D	Continuous Drain Current	-30	A
P_D	Maximum Power Dissipation	125	W
E_{AS}	Single Pulse Avalanche Energy	80	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	60	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case	1.2	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

P-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

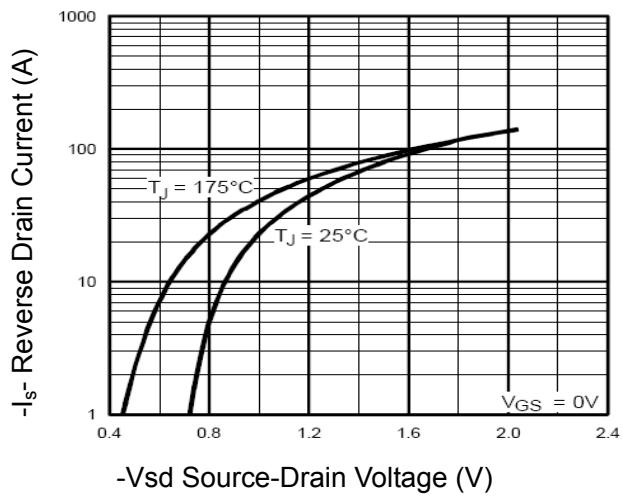
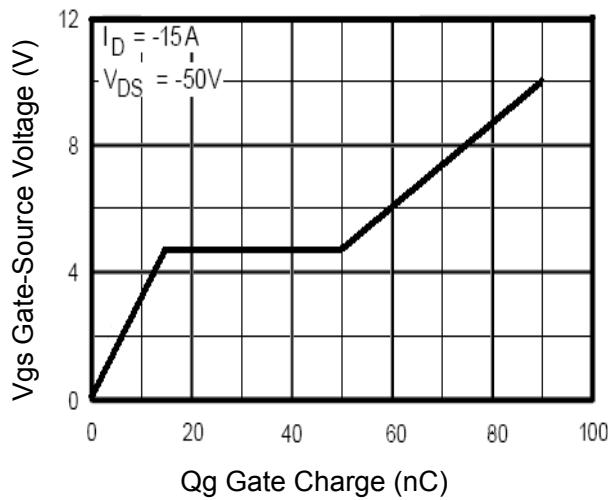
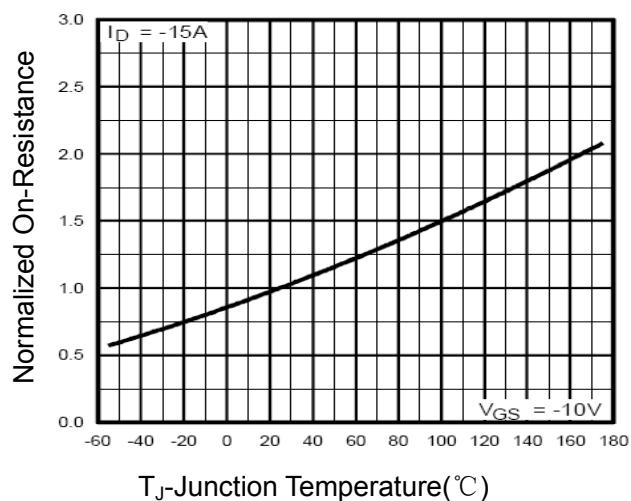
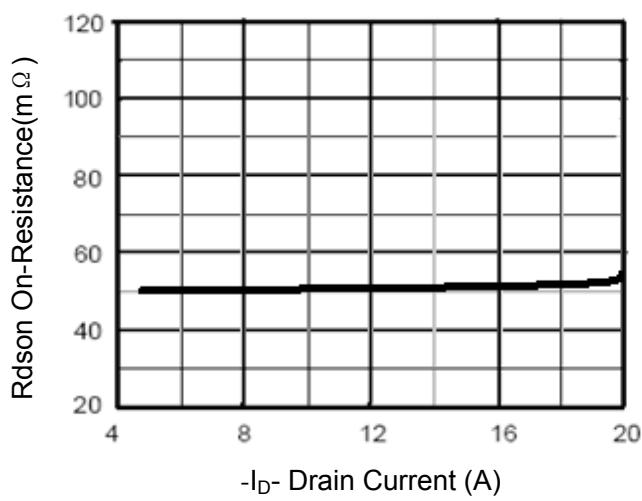
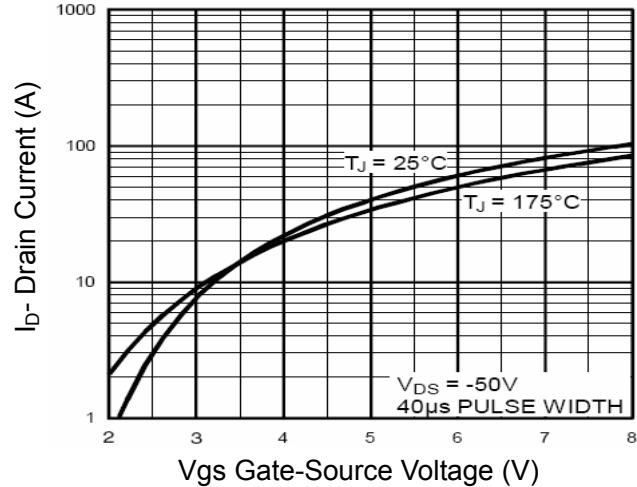
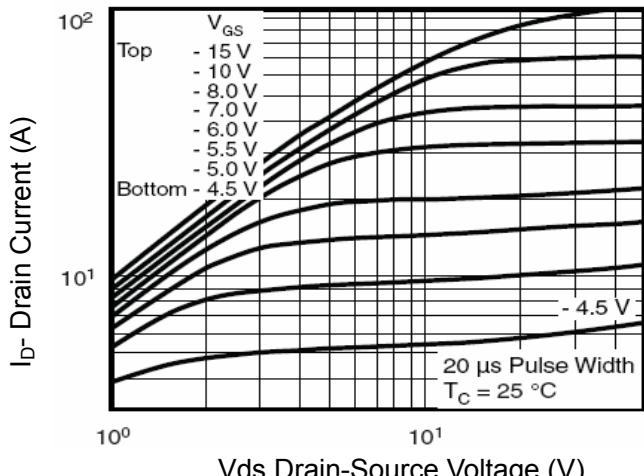
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-100	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-100\text{V}$, $V_{\text{GS}}=0\text{V}$	---	---	-1	μA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=-250\mu\text{A}$	-1.2	---	-2.5	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$R_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-15\text{A}$	---	50	58	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-8\text{A}$	---	56	66	
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-50\text{V}$, $I_{\text{D}}=-10\text{A}$	6	---	---	S
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=-25\text{V}$, Freq.=1MHz	---	2700	---	pF
C_{oss}	Output Capacitance		---	695	---	
C_{rss}	Reverse Transfer Capacitance		---	382	---	
$T_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-50\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_{\text{G}}=6\Omega$, $I_{\text{D}}=-15\text{A}$	---	17	---	nS
T_{r}	Turn-on Rise Time		---	80	---	
$T_{\text{d(off)}}$	Turn-off Delay Time		---	45	---	
T_{f}	Turn-off Fall Time		---	65	---	
Q_{g}	Total Gate Charge	$V_{\text{DS}}=-50\text{V}$, $V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-15\text{A}$	---	90	---	nC
Q_{gs}	Gate-Source Charge		---	16	---	
Q_{gd}	Gate-Drain Charge		---	35	---	
Source-Drain Characteristics						
$V_{\text{SD}}^{④}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{s}}=-10\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1.2	V

Note ④: Pulse test (pulse width 300us, duty cycle 2%).

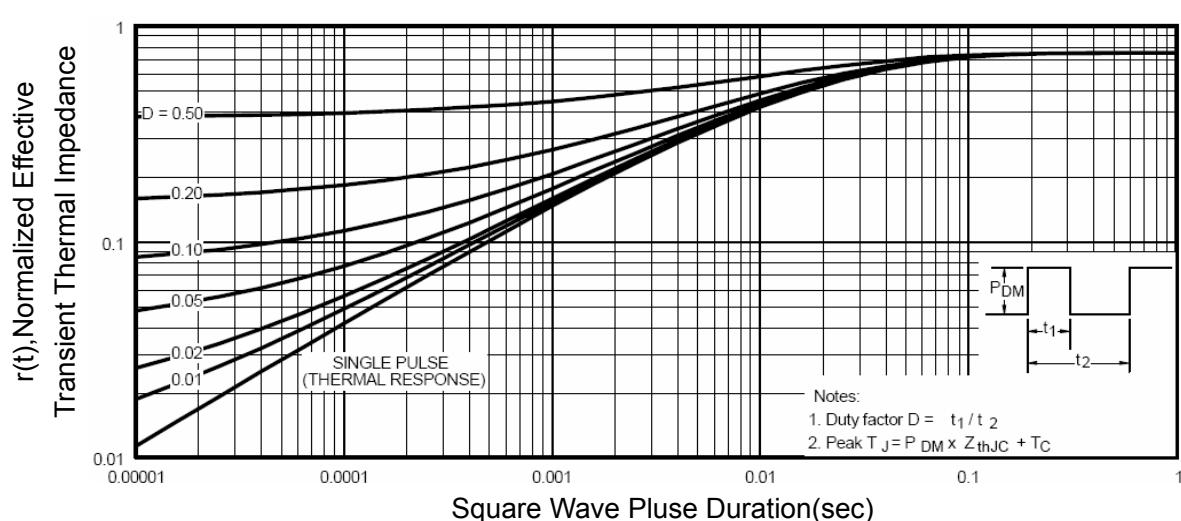
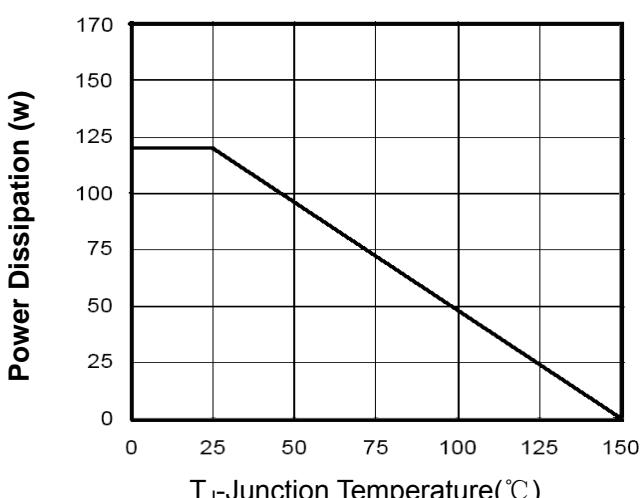
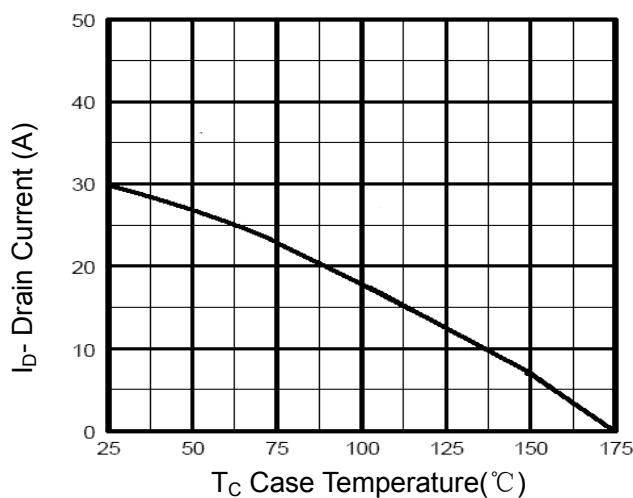
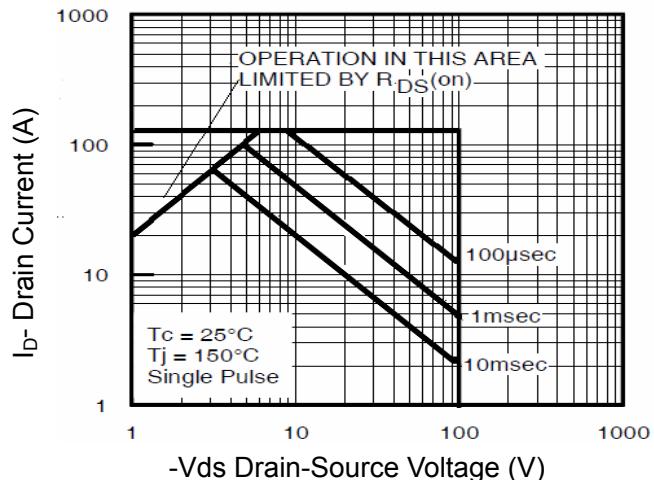
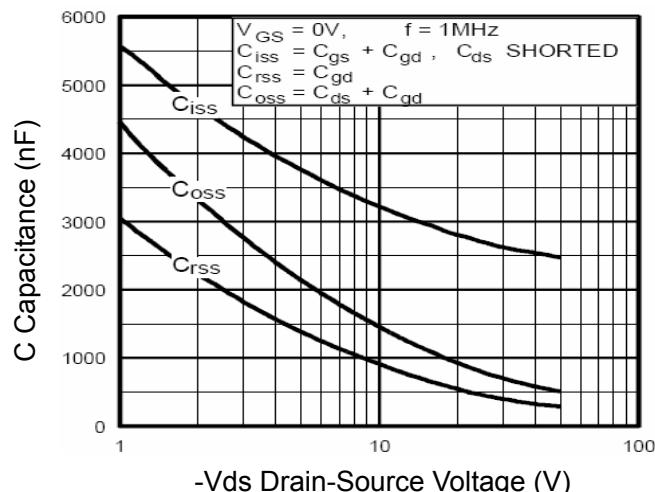
Note ⑤ : Guaranteed by design, not subject to production testing.

P-Channel Enhancement Mode MOSFET

Typical Characteristics

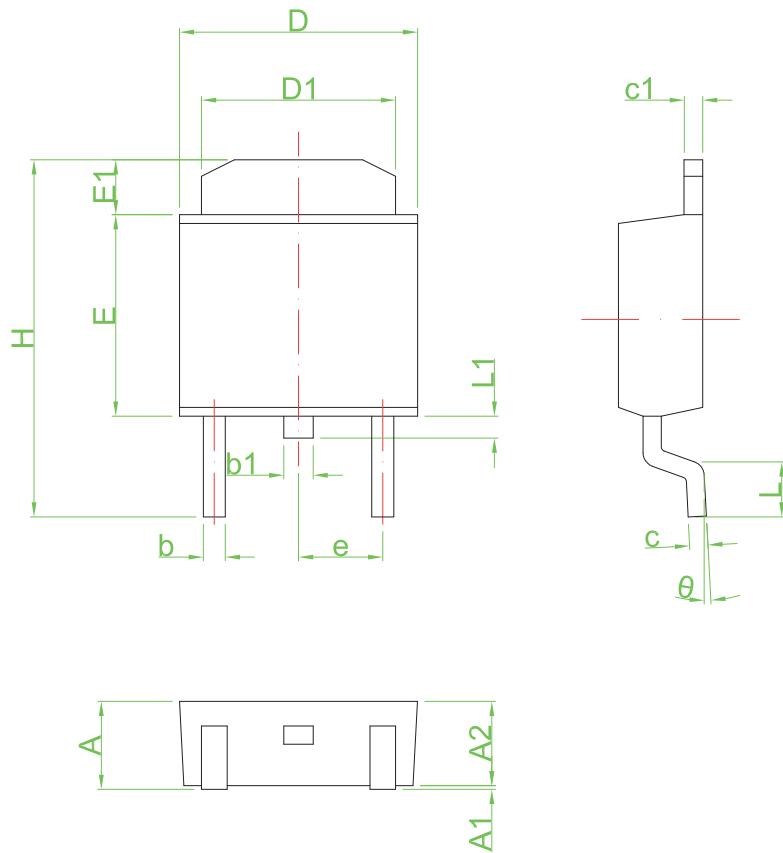


P-Channel Enhancement Mode MOSFET



P-Channel Enhancement Mode MOSFET

TO-252 Package Outline Dimensions



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	2.25	2.65	0.089	0.104
A1	0.00	0.15	0.000	0.006
A2	2.20	2.40	0.087	0.094
b	0.50	0.70	0.020	0.028
b1	0.70	0.90	0.028	0.035
c	0.46	0.66	0.018	0.026
c1	0.46	0.66	0.018	0.026
D	6.30	6.70	0.248	0.264
D1	5.20	5.40	0.205	0.213
E	5.30	5.70	0.209	0.224
E1	1.40	1.60	0.055	0.063
H	9.40	9.90	0.370	0.390
e	2.30 TYP		0.09 TYP	
L	1.40	1.77	0.055	0.070
L1	0.50	0.70	0.020	0.028
θ	0°	8°	0°	8°